

Special Issue

Fluid Flow and Heat Transfer: Latest Advances and Prospects

Message from the Guest Editors

Heat transfer and fluid flow devices are involved in many different industrial applications, coping with multiple constraints, such as reduced volumes and/or weights, lower and lower temperatures to be maintained, and, very importantly in recent years, environmental aspects. Different and complex heat transfer mechanisms are the basis of the development and design of new heat transfer devices. This Special Issue aims to cover both the fundamental mechanisms involved and the devices, covering aspects related, but not limited, to: experimental and numerical approaches for multiphase heat and mass transfer (e.g., flow boiling, pool boiling, and condensation); compact heat exchangers; microfluidics; phase change materials (PCMs); and HVAC&R systems.

Guest Editors

Dr. Andrea Diani
Dr. Marco Azzolin
Dr. Luca Viscito

Deadline for manuscript submissions

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Applied Sciences
Editorial Office
MDPI, Grosspeteranlage 5
4052 Basel, Switzerland
Tel: +41 61 683 77 34
applsci@mdpi.com

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo
Dipartimento di Fisica, Politecnico di Milano, Piazza L. da Vinci 32,
20133 Milano, Italy

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